

Which manufacturers offer COB packaging technology for optical modules



AI Overview

Major manufacturers of COB-packaged optical modules include II-VI (Finisar), Sumitomo Electric Industries, Source Photonics, Broadcom (Avago), Cisco, Intel, Lumentum (Oclaro), O-Net Technologies, ETU-LINK, Zhongji Innolight, and Eoptolink Technology.

Overview of COB Packaging for Optical Modules

COB (Chip-on-Board) packaging involves directly mounting bare optical and electrical chips onto a printed circuit board (PCB), connecting them via wire bonding, and encapsulating them with epoxy or silicone resin for protection and durability. This technology enables high-density, compact optical modules with improved thermal management, low signal loss, and cost efficiency, making it ideal for high-speed data centers, telecommunications networks, and multimode transceivers.

Key Global Manufacturers

The major global players in COB-packaged optical modules include:

- II-VI (Finisar) – Leading in high-speed optical transceivers and R&D investment.
- Sumitomo Electric Industries – Offers a wide range of optical modules with COB integration.
- Source Photonics – Focused on data center and telecom optical solutions.
- Broadcom (Avago) – Provides high-performance optical modules for enterprise and cloud networks.
- Cisco – Integrates COB technology in networking and communication devices.
- Intel – Supplies COB-based optical transceivers for high-speed applications.
- Lumentum (Oclaro) – Specializes in optical components and modules with COB packaging.
- O-Net Technologies – Offers compact, high-speed optical modules.
- ETU-LINK – Focused on cost-effective COB optical solutions.
- Zhongji Innolight – Provides optical modules for telecom and data center applications.
- Eoptolink Technology – Manufactures COB optical modules with high reliability.

Other notable manufacturers include CIG Shanghai, Linktel Technologies,...

Article Content

Comparing COB vs. BOX Packaging for Optical Modules

As technology rapidly evolves and the demand for high-speed data transmission increases, understanding the distinct packaging technologies—Chip-on-Board (COB) and

Transceiver Packaging | Broadex Technologies

Now Broadex is looking to further integrate the optical and electrical assemblies in Co-Packaged Optics (CPO) modules to meet the ever-growing need for higher data rates.

COB vs BOX transceiver packaging technology

ATGBICS and COB / BOX technology ATGBICS fibre optic transceivers are manufactured using the optimal technology and manufacturing

COB Packaging Technology of Data Center Optical

Figure 3. Application scenario of optical module in telecommunication market and data center. (a) 5G telecommunications network architecture; (b)

Comprehensive Overview of COB Packaged Optical

Key players like II-VI (Finisar), Sumitomo Electric Industries, and Lumentum (Oclaro) are heavily invested in R&D and manufacturing capabilities

Introduction To The COB Process For Optical Modules

Moduletek operates its own die bonding, wire bonding, and automatic coupling production lines, and can supply a wide range of optical module products manufactured with the

Optical device packaging technology: COB, BOX and

In the field of optical communication, the packaging of optical devices plays a crucial role in the performance and application of optical modules.

Global COB Packaged Optical Module Market Report, History and

The COB packaged optical module is a module that integrates optical devices and electronic chips through chip-on-board packaging technology.

Optical device packaging technology: COB, BOX and coaxial

Understand the key differences between COB, BOX, and coaxial optical device packaging technologies to make informed purchasing decisions with expert analysis and insights.

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The entire process can be highly automated and, because of the precise positioning of chips on the two-dimensional PCB, the difficulty of optical alignment is significantly reduced compared to FSO

COB, BOX and coaxial difference analysis

In the field of optical communication, the packaging of optical devices plays a crucial role in the performance and application of optical modules. Common optical device packaging methods

Exploring the Applications of COB and BOX Packaging

It offers a smaller package size and higher integration, enabling more compact and high-density optical module designs. Compared to box packaging, COB provides greater flexibility and

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COB Chip On Board (COB) is a relatively new type of packaging technology. It has many advantages when compared to the hermetically sealed co-axial TO can packaging of Free Space Optics (FSO).

Global COB Packaged Optical Module Supply, Demand and Key

The COB packaged optical module is a module that integrates optical devices and electronic chips through chip-on-board packaging technology. This report studies the global COB Packaged Optical

Optical Transceiver: Packaging Methods & Optical Chip

Analyzes the requirements of optical transceivers and discusses packaging methods and optical chip types to understand their design and

A Closer Look at COB and BOX Packaging in Optical Modules:

Conclusion Selecting the right packaging technology for optical modules requires a careful evaluation of the application environment, cost considerations, and performance

COB Packaged Optical Module Market Size | CAGR 12.8 Forecast 2033

The COB Packaged Optical Module market comprises chip-on-board integrated optical transceivers that combine lasers, detectors, and driver circuitry into a single, compact package for

Top 10 COB LED Package Manufacturers in the World

Well-known manufacturers such as Signify, Opble Lighting, and NVC Lighting have continuously launched smart lighting products, and COB technology has also been widely used in

High-Speed Optical Transceiver COB Packaging in

Discover the advantages of COB packaging in optical transceivers for high-speed data transmission. Learn about coupling techniques and testing

COB Packaged Optical Module in the Real World: 5 Uses You'll

The COB (Chip-On-Board) packaged optical module is a compact device that combines optical components, such as lasers and photodetectors, with electronic circuitry in a single package.

COB Packaged Optical Module in the Real World: 5 Uses You'll

COB modules typically feature low insertion loss, high reliability, and compatibility with existing optical networks. Their modular design simplifies manufacturing and maintenance, which is...

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